

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	CHENG-WEI SU	06/15/2018
RECEIVING PARTY DATA		
Name:	HONG ANN TOOL INDUSTRIES CO., LTD.	
Street Address:	NO. 307, JUNFU 19TH ROAD, BEITUN DIST.	
City:	TAICHUNG CITY	
State/Country:	TAIWAN	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Application Number:	16009309
CORRESPONDENCE DATA		
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ATTORNEY DOCKET NUMBER:	CFP-6713	
NAME OF SUBMITTER:	ALAN D. KAMRATH	
SIGNATURE:	/Alan D. Kamrath/	
DATE SIGNED:	06/15/2018	
	This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 1		
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ASSIGNMENT/DECLARATION FOR PATENT APPLICATION

WHEREAS, as a below named inventor, I hereby declare that:

My residence, mailing address, and citizenship are as stated below next to my name. I believe I am the original inventor (if only one name is listed below) or an original joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

HEAD OF BLOW GUN THAT BLOWS A LARGE AMOUNT OF AIR

the specification of which is attached hereto.

The above application was made or authorized by me.

WHEREAS Hong Ann Tool Industries Co., Ltd. of Taiwan herein referred to as "Assignee" whose mailing address is NO. 307, Junfu 19th Road, Beitun Dist., Taichung City, Taiwan

is desirous of acquiring the entire right, title and interest in and to said invention, and in and to and under any and all Letters Patent to be obtained thereon.

NOW, THEREFORE, for and in consideration of one Dollar (\$1.00) and other good and valuable considerations, the receipt of which is hereby acknowledged, I/We the inventor(s) have sold, assigned and transferred, and by these presents do hereby sell, assign and transfer unto the Assignee, its successors and assigns the entire right, title and interest in and to said invention, said application and the Letters Patent, both foreign and domestic, that may or shall issue, including all of my rights under International Convention, and I do hereby authorize and request the Commissioner of Patents and Trademarks to issue said Letters Patent to the Assignee in accordance herewith.

Upon said consideration, I/We do hereby covenant and agree with the said Assignee, its successors and assigns, that I/We will not execute any writing or do any act whatsoever conflicting with these presents, and that I/We or my/our executors or administrators will at any time upon request, without further or additional consideration, but at the expense of the said Assignee, its successors and assigns, execute such additional writings and do such additional acts as said Assignee, its successors and assigns, may deem necessary or desirable to perfect the Assignee's enjoyment of this grant, and render all necessary assistance in making application for and obtaining original, divisional, continuation, reissued or extended Letters Patent of the United States, or of any and all foreign countries on said invention, and in enforcing any rights, occurring as a result of such applications or patents, by giving testimony in any proceedings or transactions involving such applications or patents.

I hereby acknowledge that any willful false statement made in this declaration is punishable by fine or imprisonment of not more than five (5) years, or both.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Full Name of Sole or First Inventor: Cheng-Wei SU	
Residence: NO. 307, Junfu 19th Road, Beitun Dist., Taichung City, Taiwan	
Mailing Address: NO. 307, Junfu 19th Road, Beitun Dist., Taichung City, Taiwan	
Country: Taiwan	
Inventor's Signature: <i>Cheng-Wei SU</i>	Date: June 15, 2018
<input type="checkbox"/> Additional inventors are being named on the following page(s) of this sheet	